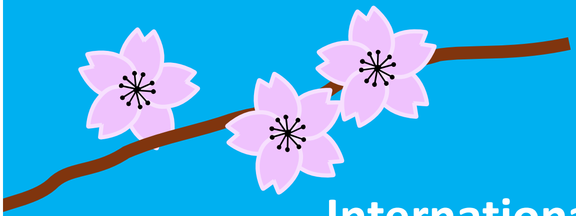
IWIPP 2027 1st CALL FOR PAPERS

International Workshop on Integrated Power Packaging 2027



IWIPP2027

Feb. 28-Mar. 4, 2027, Kitakyushu, Japan

International Conference Center, Kitakyushu, Fukuoka

This workshop aims to unite power electronics packaging researchers to advance high-density, high-efficiency power converters. We seek papers tackling challenges in power electronic components and systems, offering solutions for enhanced reliability, manufacturability, and performance at lower costs. Submissions are solicited on all power packaging topics ranging from component-level to system-level.

IWIPP TECHNICAL SCOPE

Device and Application

- Power Semiconductor Devices
- Die attach and wire bonding
- Packaging Materials
- High Temperature & High Voltage Dielectrics
- Interconnection technologies
- Printed Circuit Boards (PCB)
- High-Frequency Magnetics
- Thermal Interface Materials
- Electromagnetic Interference

Integration and Design

- Design for Manufacturability, Compatibility with Standards Innovative packaging strategies
- High-Temperature Capacitors
- System Integration and Optimization
- Compact Converter Design Techniques
- Gate/Base Drivers, Sensors & Protection

Reliability and Test

- Components to System Reliability
- Reliability Assessment & Lifetime Prediction
- Partial Discharge
- Thermal Management
- Power Cycling
- Environmental test
- Failure analysis

IWIPP2027 COMMITTEE

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IMPORTANT DATES

Abstract Submission: October 9, 2026
Notice of Acceptance: November 26, 2026
Final Paper Submission: January 18, 2027

IWIPP Portal:

http://iwipp.org/

IWIPP.ORG